



A DOCPHOENIX

Serial No. 09/577,457

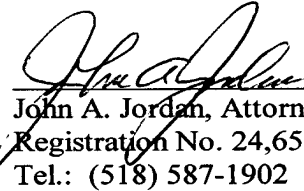
Atty. Doct No.: EN9-99-102US1

X Any additional filing fees required under 37 CFR §1.16. X Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

Mark V. Pierson, et al.

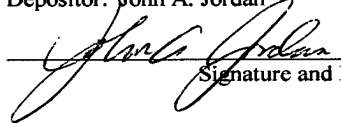
By:

  
John A. Jordan, Attorney  
Registration No. 24,655  
Tel.: (518) 587-1902

CERTIFICATE OF MAILING UNDER 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
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#8/B  
1-30-03  
JPR

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<u>In Re Application of</u>	:	January 17, 2003
<u>Mark V. Pierson, et al.</u>	:	Examiner: J.M. Mitchell
<u>Serial No.: 09/577,457</u>	:	Art Unit: 2827
<u>Filed: May 24, 2000</u>	:	IBM Corporation Intellectual Property Law
<u>Title: <b>FLOATING INTERPOSER</b></u>	:	Dept. N50/040-4, 1701 North Street Endicott, New York 13760

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Examiner's Office Action of December 3, 2002, please amend the application as follows:

**In the Claims:**

Please amend Claim 5 as follows:

- B'
- 1           5. (Twice Amended) An electronic package comprising:
  - 2           a semiconductor chip die having an array of conductive pads on one surface
  - 3   thereof;

EN9-99-102US1

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